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Details

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	<u>.</u>
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	13
Program Memory Size	1.75KB (1K x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	128 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	A/D 4x8b
Oscillator Type	External
Operating Temperature	0°C ~ 70°C (TA)
Mounting Type	Surface Mount
Package / Case	18-SOIC (0.295", 7.50mm Width)
Supplier Device Package	18-SOIC
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc712t-04-so

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PIC16C712/716

NOTES:

2.2.2.3 INTCON Register

The INTCON Register is a readable and writable register which contains various enable and flag bits for the TMR0 register overflow, RB Port change and External RB0/INT pin interrupts. **Note:** Interrupt flag bits get set when an interrupt condition occurs, regardless of the state of its corresponding enable bit or the global enable bit, GIE (INTCON<7>). User software should ensure the appropriate interrupt flag bits are clear prior to enabling an interrupt.

FIGURE 2-6: INTCON REGISTER (ADDRESS 0Bh, 8Bh)

R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-x	
GIE bit7	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF bit0	 R = Readable bit W = Writable bit U = Unimplemented bit, read as '0' -n = Value at POR Reset
bit 7:	1 = Enabl		pt Enable nasked int errupts					
bit 6:	1 = Enabl	les all unn	terrupt En nasked pe ipheral int	ripheral in	terrupts			
bit 5:	1 = Enabl	les the TM	ow Interruj 1R0 interru /IR0 interru	ıpt	bit			
bit 4:		les the RE	ternal Inte 80/INT exte 30/INT ext	ernal inter	rupt			
bit 3:	1 = Enabl	les the RE	nge Interr 8 port char 3 port cha	ige interru	pt			
bit 2:	1 = TMR0) register	ow Interrup has overflo did not ove	owed (mus	st be cleare	ed in softwa	are)	
bit 1:	1 = The F	RB0/INT e	ernal Inter xternal inte xternal inte	errupt occ	urred (mus	t be cleare	d in softwar	re)
bit 0:	1 = At lea	st one of		B4 pins cl			e cleared in	software)

Name	Bit#	Buffer	Function
RA0/AN0	bit 0	TTL	Input/output or analog input
RA1/AN1	bit 1	TTL	Input/output or analog input
RA2/AN2	bit 2	TTL	Input/output or analog input
RA3/AN3/VREF	bit 3	TTL	Input/output or analog input or VREF
			Input/output or external clock input for Timer0
RA4/T0CKI	bit 4	ST	Output is open drain type

TABLE 3-1: PORTA FUNCTIONS

Legend: TTL = TTL input, ST = Schmitt Trigger input

TABLE 3-2: SUMMARY OF REGISTERS ASSOCIATED WITH PORTA

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
05h	PORTA			_(1)	RA4	RA3	RA2	RA1	RA0	xx xxxx	xu uuuu
85h	TRISA	_	—	_(1)	PORT	A Data	Direction	Register		11 1111	11 1111
9Fh	ADCON1	_					PCFG2	PCFG1	PCFG0	000	000

Legend: x = unknown, u = unchanged, — = unimplemented locations read as '0'. Shaded cells are not used by PORTA.

Note 1: Reserved bits; Do Not Use.

TMR1 Module Mode	Clock Source	Control Bits	TMR1 Module Operation	PORTB<2:1> Operation		
Off	N/A	T1CON =xx 0x00	Off	PORTB<2:1> function as normal I/O		
Timer	Fosc/4	T1CON =xx 0x01	TMR1 module uses the main oscillator as clock source. TMR1ON can turn on or turn off Timer1.	PORTB<2:1> function as normal I/O		
Counter	External circuit	T1CON =xx 0x11 TR1SCCP =x-1	TMR1 module uses the external signal on the RB1/T1OSO/ T1CKI pin as a clock source. TMR1ON can turn on or turn off Timer1. DT1CK can read the signal on the RB1/T1OSO/ T1CKI pin.	PORTB<2> functions as normal I/O. PORTB<1> always reads '0' when configured as input. If PORTB<1> is configured as out- put, reading PORTB<1> will read the data latch. Writing to PORTB<1> will always store the		
	Firmware	T1CON =xx 0x11 TR1SCCP =x-0	DATACCP<0> bit drives RB1/ T1OSO/T1CKI and produces the TMR1 clock source. TMR1ON can turn on or turn off Timer1. The DATACCP<0> bit, DT1CK, can read and write to the RB1/T1OSO/T1CKI pin.	result in the data latch, but not to the RB1/T1OSO/T1CKI pin. If the TMR1CS bit is cleared (TMR1 reverts to the timer mode), then pin PORTB<1> will be driven with the value in the data latch.		
	Timer1 oscillator	T1CON =xx 1x11	RB1/T1OSO/T1CKI and RB2/ T1OSI are configured as a 2 pin crystal oscillator. RB1/T1OSI/ T1CKI is the clock input for TMR1. TMR1ON can turn on or turn off Timer1. DATACCP<1> bit, DT1CK, always reads '0' as input and can not write to the RB1/T1OSO/T1CK1 pin.	PORTB<2:1> always read '0' when configured as inputs. If PORTB<2:1> are configured as outputs, reading PORTB<2:1> will read the data latches. Writ- ing to PORTB<2:1> will always store the result in the data latches, but not to the RB2/ T1OSI and RB1/T1OSO/T1CKI pins. If the TMR1CS and T1OSCEN bits are cleared (TMR1 reverts to the timer mode and TMR1 oscillator is disabled), then pin PORTB<2:1> will be driven with the value in the data latches.		

TABLE 5-1: TMR1 MODULE AND PORTB OPERATION

5.3 Timer1 Oscillator

A crystal oscillator circuit is built in between pins T1OSI (input) and T1OSO (amplifier output). It is enabled by setting control bit T1OSCEN (T1CON<3>). The oscillator is a low-power oscillator rated up to 200 kHz. It will continue to run during Sleep. It is primarily intended for a 32 kHz crystal. Table 5-2 shows the capacitor selection for the Timer1 oscillator.

The Timer1 oscillator is identical to the LP oscillator. The user must provide a software time delay to ensure proper oscillator start-up.

TABLE 5-2:CAPACITOR SELECTION FOR
THE TIMER1 OSCILLATOR

Osc Type	Freq.	C1	C2						
LP	32 kHz	33 pF	33 pF						
	100 kHz	15 pF	15 pF						
	200 kHz	15 pF							
These v	These values are for design guidance only.								
Note 1: Higl	her capacitand	ce increases th	ne stability of						

oscillator but also increases the start-up time.

2: Since each resonator/crystal has its own characteristics, the user should consult the resonator/crystal manufacturer for appropriate values of external components.

5.4 Timer1 Interrupt

The TMR1 Register pair (TMR1H:TMR1L) increments from 0000h to FFFFh and rolls over to 0000h. The TMR1 interrupt, if enabled, is generated on overflow which is latched in interrupt flag bit TMR1IF (PIR1<0>). This interrupt can be enabled/disabled by setting/clearing TMR1 interrupt enable bit TMR1IE (PIE1<0>).

5.5 Resetting Timer1 using a CCP Trigger Output

If the CCP module is configured in Compare mode to generate a "Special Event Trigger" (CCP1M3:CCP1M0 = 1011), this signal will reset Timer1 and start an A/D conversion (if the A/D module is enabled).

Note:	The Special Event Triggers from the
	CCP1 module will not set interrupt flag bit
	TMR1IF (PIR1<0>).

Timer1 must be configured for either Timer or Synchronized Counter mode to take advantage of this feature. If Timer1 is running in Asynchronous Counter mode, this reset operation may not work.

In the event that a write to Timer1 coincides with a Special Event Trigger from CCP1, the write will take precedence.

In this mode of operation, the CCPR1H:CCPR1L registers pair effectively becomes the period register for Timer1.

Value on Value on Address Name Bit 7 Bit 6 Bit 5 Bit 4 Bit 3 Bit 1 Bit 0 POR, all other Bit 2 BOR Resets 0Bh,8Bh INTCON GIE PEIE TOIE INTE RBIE **T0IF** INTE RBIF 0000 000x 0000 000u -0---000 -0---000 0Ch PIR1 ADIF CCP1IF TMR2IF TMR1IF -0---000 -0---000 8Ch PIE1 ADIE CCP1IE TMR2IE TMR1IE 0Eh TMR1L Holding Register for the Least Significant Byte of the 16-bit TMR1 Register XXXX XXXX uuuu uuuu 0Fh TMR1H Holding Register for the Most Significant Byte of the 16-bit TMR1 Register XXXX XXXX uuuu uuuu --00 0000 --uu uuuu T1CKPS1 T1CKPS0 T1OSCEN T1SYNC 10h T1CON ____ ____ TMR1CS TMR10N -x-x _ _ _ _ -11-11 07h DATACC DCCP DT1CK Р ---- -1-1 ---- -1-1 87h TRISCCP TCCP TT1CK

TABLE 5-3: REGISTERS ASSOCIATED WITH TIMER1 AS A TIMER/COUNTER

Legend: x = unknown, u = unchanged, --- = unimplemented read as '0'. Shaded cells are not used by the Timer1 module.

6.0 TIMER2 MODULE

The Timer2 module timer has the following features:

- 8-bit timer (TMR2 register)
- 8-bit period register (PR2)
- Readable and writable (both registers)
- Software programmable prescaler (1:1, 1:4, 1:16)
- Software programmable postscaler (1:1 to 1:16)
- Interrupt on TMR2 match of PR2

Timer2 has a control register, shown in Figure 6-1. Timer2 can be shut off by clearing control bit TMR2ON (T2CON<2>) to minimize power consumption.

Figure 6-2 is a simplified block diagram of the Timer2 module.

Additional information on timer modules is available in the PIC[®] Mid-Range Reference Manual, (DS33023).

FIGURE 6-1: T2CON: TIMER2 CONTROL REGISTER (ADDRESS 12h)

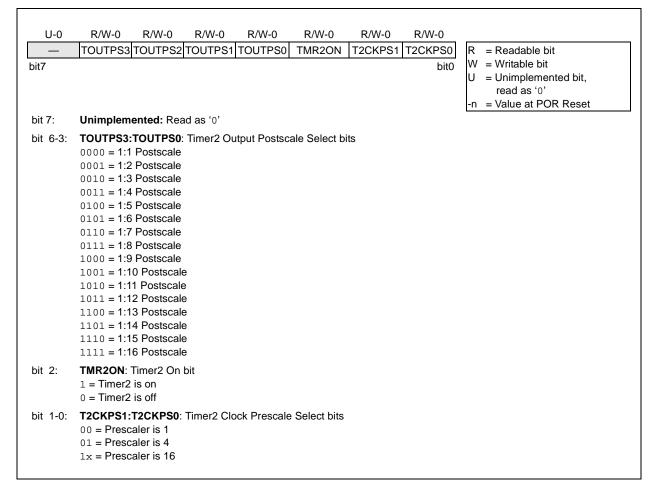
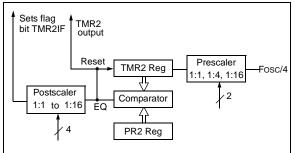


FIGURE 6-2: TIMER2 BLOCK DIAGRAM



7.3.3 SET-UP FOR PWM OPERATION

The following steps should be taken when configuring the CCP module for PWM operation:

- 1. Set the PWM period by writing to the PR2 register.
- 2. Set the PWM duty cycle by writing to the CCPR1L register and CCP1CON<5:4> bits.
- 3. Make the CCP1 pin an output by clearing the TRISCCP<2> bit.
- 4. Set the TMR2 prescale value and enable Timer2 by writing to T2CON.
- 5. Configure the CCP1 module for PWM operation.

TABLE 7-3:EXAMPLE PWM FREQUENCIES AND RESOLUTIONS AT 20 MHz

PWM Frequency	1.22 kHz	4.88 kHz	19.53 kHz	78.12 kHz	156.3 kHz	208.3 kHz
Timer Prescaler (1, 4, 16)	16	4	1	1	1	1
PR2 Value	0xFF	0xFF	0xFF	0x3F	0x1F	0x17
Maximum Resolution (bits)	10	10	10	8	7	5.5

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR, BOR	Value on all other Resets
07h	DATACCP	—	_				DCCP		DT1CK	xxxx xxxx	xxxx xuxu
0Bh,8Bh	INTCON	GIE	PEIE	TOIE	INTE	RBIE	TOIF	INTF	RBIF	0000 000x	0000 000u
0Ch	PIR1	—	ADIF	_	_	_	CCP1IF	TMR2IF	TMR1IF	-0000	-0000
11h	TMR2	Timer2 Mc	dule's Regis	ter						0000 0000	0000 0000
12h	T2CON	—	TOUTPS3	TOUTPS2	TOUTPS1	TOUTPS0	TMR2ON	T2CKPS1	T2CKPS0	-000 0000	-000 0000
15h	CCPR1L	Capture/C	ompare/PWI	V Register 1	(LSB)					xxxx xxxx	uuuu uuuu
16h	CCPR1H	Capture/C	ompare/PWI	VI Register 1	(MSB)					xxxx xxxx	uuuu uuuu
17h	CCP1CON	—	_	DC1B1	DC1B0	CCP1M3	CCP1M2	CCP1M1	CCP1M0	00 0000	00 0000
87h	TRISCCP	—		_	_	_	TCCP	_	TT1CK	xxxx x1x1	xxxx x1x1
8Ch	PIE1	—	ADIE	_	_	_	CCP1IE	TMR2IE	TMR1IE	-0000	-0000
92h	PR2	Timer2 Mc	dule's Period		1111 1111	1111 1111					

TABLE 7-4: REGISTERS ASSOCIATED WITH PWM AND TIMER2

Legend: x = unknown, u = unchanged, — = unimplemented read as '0'. Shaded cells are not used by PWM and Timer2.

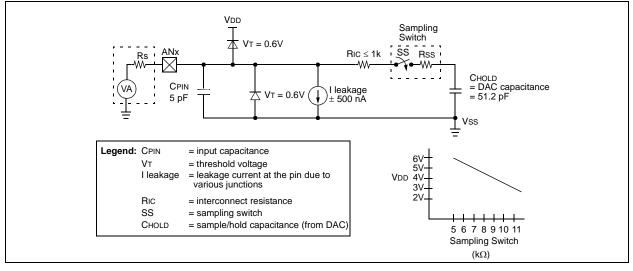
8.1 A/D Acquisition Requirements

For the A/D converter to meet its specified accuracy, the Charge Holding capacitor (CHOLD) must be allowed to fully charge to the input channel voltage level. The analog input model is shown in Figure 8-4. The source impedance (Rs) and the internal sampling switch (Rss) impedance directly affect the time required to charge the capacitor CHOLD. The sampling switch (Rss) impedance varies over the device voltage (VDD). The source impedance affects the offset voltage at the analog input (due to pin leakage current). The maximum recommended impedance for analog sources is 10 k Ω . After the analog input channel is selected (changed) this acquisition must be done before the conversion can be started.

To calculate the minimum acquisition time, TACQ, see the PIC[®] Mid-Range Reference Manual, (DS33023). This equation calculates the acquisition time to within 1/2 LSb error (512 steps for the A/D). The 1/2 LSb error is the maximum error allowed for the A/D to meet its specified accuracy.

Note: When the conversion is started, the holding capacitor is disconnected from the input pin.

FIGURE 8-4: ANALOG INPUT MODEL



8.2 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 9.5TAD per 8-bit conversion. The source of the A/D conversion clock is software selectable. The four possible options for TAD are:

- 2Tosc
- 8Tosc
- 32Tosc
- Internal RC oscillator

For correct A/D conversions, the A/D conversion clock (TAD) must be selected to ensure a minimum TAD time of 1.6 $\mu s.$

Table 8-1 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

8.3 Configuring Analog Port Pins

The ADCON1 and TRISA registers control the operation of the A/D port pins. The port pins that are desired as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS2:CHS0 bits and the TRIS bits.

- Note 1: When reading the port register, all pins configured as analog input channels will read as cleared (a low level). Pins configured as digital inputs, will convert an analog input. Analog levels on a digitally configured input will not affect the conversion accuracy.
 - 2: Analog levels on any pin that is defined as a digital input (including the AN3:AN0 pins), may cause the input buffer to consume current that is out of the devices specification.

TABLE 8-1: TAD vs. DEVICE OPERATING FREQUENCIES

AD Clock	Source (TAD)	Device Frequency							
Operation	ADCS1:ADCS0	20 MHz	5 MHz	1.25 MHz	333.33 kHz				
2Tosc	00	100 ns ⁽²⁾	400 ns ⁽²⁾	1.6 μs	6 μs				
8Tosc	01	400 ns ⁽²⁾	1.6 μs	6.4 μs	24 μs ⁽³⁾				
32Tosc	10	1.6 μs	6.4 μs	25.6 μs ⁽³⁾	96 μs (3)				
RC ⁽⁵⁾	11	2-6 μs ^(1,4)	2-6 μs ^(1,4)	2-6 μs ^(1,4)	2-6 μs ⁽¹⁾				

Legend: Shaded cells are outside of recommended range.

Note 1: The RC source has a typical TAD time of 4 μ s.

- **2:** These values violate the minimum required TAD time.
- **3:** For faster conversion times, the selection of another clock source is recommended.
- 4: When device frequency is greater than 1 MHz, the RC A/D conversion clock source is recommended for Sleep operation only.

5: For extended voltage devices (LC), please refer to Electrical Specifications section.

FIGURE 9-1: CONFIGURATION WORD

													•	
CP1	CPO	CP1	CP0	CP1	CP0	—	BODEN	CP1	CP0	PWRTE	WDTE	FOSC1	FOSC0	Register:CONFIG
bit13													bit0	Address2007h
bit 12	0 0 5	-4: CP1		Codo	Droto	otion k	oite (2)							
DILTO	J-0, J						ram mem	orv (P	10.160	(716)				
							tection of		10100	,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,				
			= 0400											
			= 0200											
			= 0000			•								
bit 13	3-8, 5	-4:												
		Coc	le Prot	ection	for 1k	(Prog	ram mem	ory bi	ts (PIC	C16C712)				
		11:	= Prog	rammi	ing coo	de pro	tection of	f						
			•		•	•	tection of	f						
			= 0200			•								
		00 :	= 0000	h-03F	Fh coo	de-pro	tected							
bit 7		11			J. D	-l ()	.,							
bit 6	-						ı nable bit	(1)						
DIL U.	•		BOR 6					()						
		_	BOR											
bit 3		-				ner Fr	hable bit (1)						
511 0	•		PWRT		•									
		-	PWRT											
bit 2	:	WD	TE: W	atchdo	og Tim	er Ena	able bit							
		1 =	WDT (enable	ed									
		0 =	WDT (disable	əd									
bit 1-	-0:	FOS	SC1:F	OSC0:	: Oscill	ator S	election b	oits						
		11:	= RC c	oscillat	or									
		10:	= HS o	scillat	or									
		01:	= XT o	scillato	or									
		00:	= LP o	scillato	or									
Note	4.	Enabli	na Bro			at outo	matically	onabl			mor (D\//		diace of th	
note			-							vn-out Re		, .	uiess 01 (f	he value of bit PWRTE.
	2:												ntection s	cheme listed.
	۷.			1.01 0	Pairs	nave	o bo give	in une	Same					

9.9 Power Control/Status Register (PCON)

The Power Control/Status Register, PCON has two bits.

Bit 0 is Brown-out Reset Status bit, $\overline{\text{BOR}}$. If the BODEN Configuration bit is set, $\overline{\text{BOR}}$ is '1' on Power-on Reset. If the BODEN Configuration bit is clear, $\overline{\text{BOR}}$ is unknown on Power-on Reset. The BOR Status bit is a "don't care" and is not necessarily predictable if the brown-out circuit is disabled (the BODEN Configuration bit is clear). BOR must then be set by the user and checked on subsequent Resets to see if it is clear, indicating a brown-out has occurred.

Bit 1 is $\overrightarrow{\text{POR}}$ (Power-on Reset Status bit). It is cleared on a Power-on Reset and unaffected otherwise. The user must set this bit following a Power-on Reset.

TABLE 9-3:TIME-OUT IN VARIOUS SITUATIONS

Oscillator Configuration	Power	-up	Brown-out	Wake-up from
	PWRTE = 0	PWRTE = 1	Brown-out	Sleep
XT, HS, LP	72 ms + 1024Tosc	1024Tosc	72 ms + 1024Tosc	1024Tosc
RC	72 ms		72 ms	—

TABLE 9-4: STATUS BITS AND THEIR SIGNIFICANCE

POR	BOR	TO	PD	
0	x	1	1	Power-on Reset
0	x	0	x	Illegal, TO is set on POR
0	x	x	0	Illegal, PD is set on POR
1	0	1	1	Brown-out Reset
1	1	0	1	WDT Reset
1	1	0	0	WDT Wake-up
1	1	u	u	MCLR Reset during normal operation
1	1	1	0	MCLR Reset during Sleep or interrupt wake-up from Sleep

TABLE 9-5: RESET CONDITION FOR SPECIAL REGISTERS

Condition	Program Counter	STATUS Register	PCON Register
Power-on Reset	000h	0001 1xxx	0x
MCLR Reset during normal operation	000h	000u uuuu	uu
MCLR Reset during Sleep	000h	0001 Ouuu	uu
WDT Reset	000h	0000 luuu	uu
WDT Wake-up	PC + 1	uuu0 Ouuu	uu
Brown-out Reset	000h	0001 luuu	u0
Interrupt wake-up from Sleep	PC + 1 ⁽¹⁾	uuul Ouuu	uu

Legend: u = unchanged, x = unknown, - = unimplemented bit read as '0'.

Note 1: When the wake-up is due to an interrupt and the GIE bit is set, the PC is loaded with the interrupt vector (0004h).

9.12 Watchdog Timer (WDT)

The Watchdog Timer is as a free running, on-chip, RC oscillator which does not require any external components. This RC oscillator is separate from the RC oscillator of the OSC1/CLKIN pin. That means that the WDT will run, even if the clock on the OSC1/CLKIN and OSC2/CLKOUT pins of the device have been stopped, for example, by execution of a SLEEP instruction.

During normal operation, a WDT Time-out generates a device Reset (Watchdog Timer Reset). If the device is in Sleep mode, a WDT Time-out causes the device to wake-up and continue with normal operation (Watchdog Timer Wake-up). The TO bit in the STATUS register will be cleared upon a Watchdog Timer Time-out.

The WDT can be permanently disabled by clearing Configuration bit WDTE (**Section 9.1 "Configuration Bits**").

WDT time-out period values may be found in the Electrical Specifications section under TwDT (parameter #31). Values for the WDT prescaler (actually a postscaler, but shared with the Timer0 prescaler) may be assigned using the OPTION_REG register.

Note: The CLRWDT and SLEEP instructions clear the WDT and the postscaler, if assigned to the WDT, and prevent it from timing out and generating a device Reset condition.

Note: When a CLRWDT instruction is executed and the prescaler is assigned to the WDT, the prescaler count will be cleared, but the prescaler assignment is not changed.

FIGURE 9-15: WATCHDOG TIMER BLOCK DIAGRAM

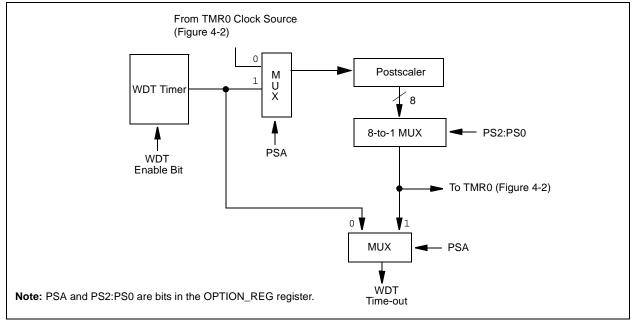


FIGURE 9-16: SUMMARY OF WATCHDOG TIMER REGISTERS

Address	Name	Bits 13:8	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0
2007h	Config. bits	(1)		BODEN ⁽¹⁾	CP1	CP0	PWRTE ⁽¹⁾	WDTE	FOSC1	FOSC0
81h	OPTION_REG	N/A	RBPU	INTEDG	TOCS	T0SE	PSA	PS2	PS1	PS0

Legend: Shaded cells are not used by the Watchdog Timer. **Note 1:** See Figure 9-1 for operation of these bits.

When the SLEEP instruction is being executed, the next instruction (PC + 1) is pre-fetched. For the device to wake-up through an interrupt event, the corresponding interrupt enable bit must be set (enabled). Wake-up is regardless of the state of the GIE bit. If the GIE bit is clear (disabled), the device continues execution at the instruction after the SLEEP instruction. If the GIE bit is set (enabled), the device executes the instruction after the SLEEP instruction and then branches to the interrupt address (0004h). In cases where the execution of the instruction following SLEEP is not desirable, the user should have a NOP after the SLEEP instruction.

WAKE-UP USING INTERRUPTS 9.13.2

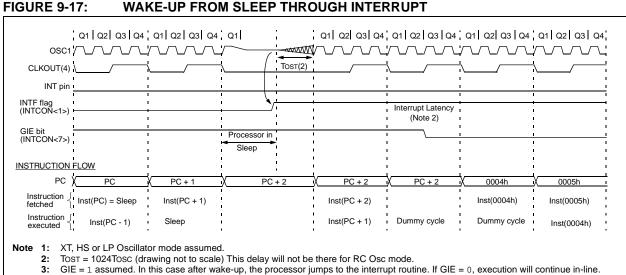
When global interrupts are disabled (GIE cleared) and any interrupt source has both its interrupt enable bit and interrupt flag bit set, one of the following will occur:

· If the interrupt occurs before the execution of a SLEEP instruction, the SLEEP instruction will complete as a NOP. Therefore, the WDT and WDT postscaler will not be cleared, the \overline{TO} bit will not be set and \overline{PD} bits will not be cleared.

• If the interrupt occurs during or after the execution of a SLEEP instruction, the device will immediately wake-up from Sleep. The SLEEP instruction will be completely executed before the wake-up. Therefore, the WDT and WDT postscaler will be cleared, the TO bit will be set and the \overline{PD} bit will be cleared.

Even if the flag bits were checked before executing a SLEEP instruction, it may be possible for flag bits to become set before the SLEEP instruction completes. To determine whether a SLEEP instruction executed, test the PD bit. If the PD bit is set, the SLEEP instruction was executed as a NOP.

To ensure that the WDT is cleared, a CLRWDT instruction should be executed before a **SLEEP** instruction.



4:

CLKOUT is not available in these osc modes, but shown here for timing reference.

9.14 Program Verification/Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note:	Microchip	does	not	recommend	code
	protecting	window	ved c	levices.	

ID Locations 9.15

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution, but are readable and writable during Program/Verify. It is recommended that only the 4 Least Significant bits of the ID location are used.

For ROM devices, these values are submitted along with the ROM code.

9.16 In-Circuit Serial Programming™

PIC16CXXX microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

For complete details on serial programming, please refer to the In-Circuit Serial Programming[™] (ICSP[™]) Guide, (DS30277).

11.11 PICSTART Plus Development Programmer

The PICSTART Plus Development Programmer is an easy-to-use, low-cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient. The PICSTART Plus Development Programmer supports most PIC devices in DIP packages up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus Development Programmer is CE compliant.

11.12 Demonstration, Development and Evaluation Boards

A wide variety of demonstration, development and evaluation boards for various PIC MCUs and dsPIC DSCs allows quick application development on fully functional systems. Most boards include prototyping areas for adding custom circuitry and provide application firmware and source code for examination and modification.

The boards support a variety of features, including LEDs, temperature sensors, switches, speakers, RS-232 interfaces, LCD displays, potentiometers and additional EEPROM memory.

The demonstration and development boards can be used in teaching environments, for prototyping custom circuits and for learning about various microcontroller applications.

In addition to the PICDEM[™] and dsPICDEM[™] demonstration/development board series of circuits, Microchip has a line of evaluation kits and demonstration software for analog filter design, KEELOQ[®] security ICs, CAN, IrDA[®], PowerSmart[®] battery management, SEEVAL[®] evaluation system, Sigma-Delta ADC, flow rate sensing, plus many more.

Check the Microchip web page (www.microchip.com) and the latest *"Product Selector Guide"* (DS00148) for the complete list of demonstration, development and evaluation kits.

12.3 DC Characteristics: PIC16C712/716-04 (Commercial, Industrial, Extended) PIC16C712716-20 (Commercial, Industrial, Extended) PIC16LC712/716-04 (Commercial, Industrial)

	Standard Operating Conditions (unless otherwise stated)									
			Operating		rature	≥ O°C 2°0 ≤	$TA \leq +70^{\circ}C$ for commercial			
					-4(≥ O°C	$TA \leq +125^{\circ}C$ for extended			
DC CHA	RACTE	RISTICS	Operating	voltage	e VDD rang	e as de	escribed in DC spec Section 12.1			
			"DC Characteristics: PIC16C712/716-04 (Commercial, Industrial,							
							ommercial, Industrial,			
			Extended 716-04 (C				Characteristics: PIC16LC712/			
_										
Param	Sym.	Characteristic	Min.	Тур†	Max.	Units	Conditions			
No.										
		Input Low Voltage								
	VIL	I/O ports								
D030		with TTL buffer	Vss	—	0.8V	V	$4.5V \leq VDD \leq 5.5V$			
D030A			Vss	—	0.15Vdd	V	otherwise			
D031		with Schmitt Trigger buffer	Vss	—	0.2VDD	V				
D032		MCLR, OSC1 (in RC mode)	Vss	—	0.2Vdd	V				
D033		OSC1 (in XT, HS and LP modes)	Vss	_	0.3Vdd	V	(Note 1)			
		Input High Voltage								
	Vін	I/O ports		—						
D040		with TTL buffer	2.0	—	Vdd	V	$4.5V \leq V\text{DD} \leq 5.5V$			
D040A			0.25Vdd	—	Vdd	V	otherwise			
			+ 0.8V							
D041		with Schmitt Trigger buffer	0.8Vdd	_	Vdd	V	For entire VDD range			
D042		MCLR	0.8Vdd	—	Vdd	V				
D042A		OSC1 (XT, HS and LP modes)	0.7Vdd	—	Vdd	V	(Note 1)			
D043		OSC1 (in RC mode)	0.9Vdd	—	Vdd	V				
		Input Leakage Current (Notes 2, 3)								
D060	lı∟	I/O ports	-	—	±1	μA	$Vss \leq VPIN \leq VDD$,			
DOC1					LE.	۸	Pin at high-impedance Vss \leq VPIN \leq VDD			
D061		MCLR, RA4/T0CKI		_	±5	μA				
D063		OSC1		_	±5	μA	Vss \leq VPIN \leq VDD, XT, HS and LP osc modes			
D070	IPURB	PORTB weak pull-up current	50	250	400	μA	VDD = 5V, VPIN = VSS			
5010	IFURB	FOR TO weak pull-up cultent	50	200	400	μΑ	$v_{DD} = 5v, v_{PIN} = v_{55}$			

These parameters are characterized but not tested.

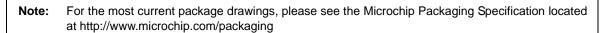
† Data in "Typ" column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

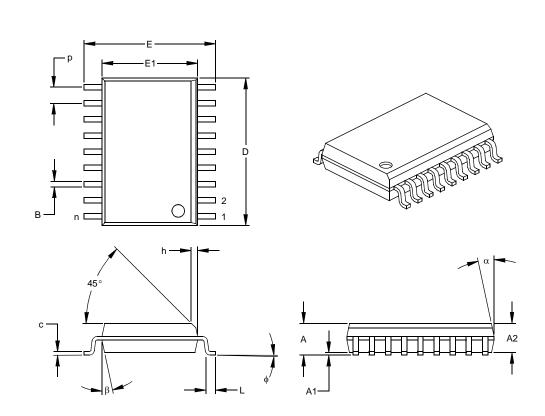
Note 1: In RC Oscillator mode, the OSC1/CLKIN pin is a Schmitt Trigger input. It is not recommended that the PIC MCU be driven with external clock in RC mode.

2: The leakage current on the MCLR/VPP pin is strongly dependent on the applied voltage level. The specified levels represent normal operating conditions. Higher leakage current may be measured at different input voltages.

3: Negative current is defined as current sourced by the pin.







	Units		INCHES*		MILLIMETERS			
Dimensi	MIN	NOM	MAX	MIN	NOM	MAX		
Number of Pins	n		18			18		
Pitch	р		.050			1.27		
Overall Height	А	.093	.099	.104	2.36	2.50	2.64	
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39	
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30	
Overall Width	Е	.394	.407	.420	10.01	10.34	10.67	
Molded Package Width	E1	.291	.295	.299	7.39	7.49	7.59	
Overall Length	D	.446	.454	.462	11.33	11.53	11.73	
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74	
Foot Length	L	.016	.033	.050	0.41	0.84	1.27	
Foot Angle	¢	0	4	8	0	4	8	
Lead Thickness	С	.009	.011	.012	0.23	0.27	0.30	
Lead Width	В	.014	.017	.020	0.36	0.42	0.51	
Mold Draft Angle Top	α	0	12	15	0	12	15	
Mold Draft Angle Bottom	β	0	12	15	0	12	15	

* Controlling Parameter § Significant Characteristic

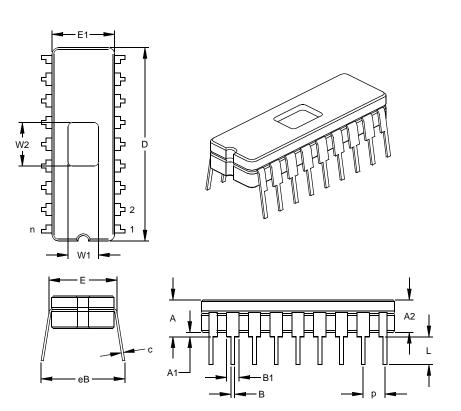
Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MS-013

Drawing No. C04-051

18-Lead Ceramic Dual In-line with Window (JW) - 300 mil (CERDIP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units				MILLIMETERS			
Dimensio	MIN	NOM	MAX	MIN	NOM	MAX		
Number of Pins	n		18			18		
Pitch	р		.100			2.54		
Top to Seating Plane	Α	.170	.183	.195	4.32	4.64	4.95	
Ceramic Package Height	A2	.155	.160	.165	3.94	4.06	4.19	
Standoff	A1	.015	.023	.030	0.38	0.57	0.76	
Shoulder to Shoulder Width	E	.300	.313	.325	7.62	7.94	8.26	
Ceramic Pkg. Width	E1	.285	.290	.295	7.24	7.37	7.49	
Overall Length	D	.880	.900	.920	22.35	22.86	23.37	
Tip to Seating Plane	L	.125	.138	.150	3.18	3.49	3.81	
Lead Thickness	С	.008	.010	.012	0.20	0.25	0.30	
Upper Lead Width	B1	.050	.055	.060	1.27	1.40	1.52	
Lower Lead Width	В	.016	.019	.021	0.41	0.47	0.53	
Overall Row Spacing §	eB	.345	.385	.425	8.76	9.78	10.80	
Window Width	W1	.130	.140	.150	3.30	3.56	3.81	
Window Length	W2	.190	.200	.210	4.83	5.08	5.33	

* Controlling Parameter
 § Significant Characteristic
 JEDEC Equivalent: MO-036
 Drawing No. C04-010

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